| ASSOCIATION CONNECTING<br>ELECTROMICS INDUSTRIES®<br>MOUSTRIES®<br>MOUSTRIES®<br>MOUSTRIES® | ourn. Illinois. All rights reserved und                   | der both This docum level parts, t | ent is a declaration<br>the declaration end | n of the substance<br>compasses all low                                       | s within the manufacture<br>er level materials for wh | er listed item. Note: if<br>nich the manufacturer l | the item is an as<br>has engineering | sembly with lower responsibility. |  |
|---|---|------------------------------------|---|---|---|---|--------------------------------------|-----------------------------------|--|
| IPC Web Site for Information on I   http://www.ipc.org/IPC-175x                             | for Information on IPC-1752 Standard Form Type Distribute |                                    |   | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg I |   |   |                                      |                                   |  |
| Supplier Information  |   |                                    |   |   |   |   |                                      |                                   |  |
| Company name*   | Company unique ID   |                                    | Unique ID Authority                         |   |   | Response Date*                                      |                                      |                                   |  |
| onsemi  |   |                                    |   |   |   | 2023-06-08  |                                      |                                   |  |
| Contact Name  | Title - Contact   |                                    | Phone - Contact*                            |   |   | Email - Contact*                                    |                                      |                                   |  |
| Product-Env-Stewards  | Product Enviro Compliance                                 |                                    | NA  |   |   | Product-Env-Stewards@onsemi.com                     |                                      |                                   |  |
| Authorized Representative*  | Title - Representative                                    |                                    | Phone - Representative*                     |   |   | Email - Representative*                             |                                      |                                   |  |
| Product-Env-Stewards Product Enviro Compliance  |   |                                    | NA  |   |   | Product-Env-Stewards@onsemi.com                     |                                      |                                   |  |
| Requester Item Number Mfr Item  | Number Mfr Item Name                                      |                                    | Effective Date                              | Version   | Manufacturing Site                                    | Weight*   | UOM                                  | Unit Type                         |  |
| H11A1S  | M 6PW TR SMD  |                                    | 2023-06-08                                  |   | LITEONFG  | 464.903   | mg                                   | Each                              |  |
| Manufacturing Proccess Information  |   |                                    |   |   |   |   |                                      |                                   |  |
| Terminal Plating / Grid Array Material  | Cerminal Base Alloy J-S                                   | STD-020 MSL Rating                 | Peak Process Body Temperature Max T         |   | ure Max Time at Peak                                  | Temperature Numbe                                   | r of Reflow Cyc                      | les                               |  |
| Matte Tin (Sn) - annealed CU Alloy 1  |   |                                    | 260   | С   | 30  | seconds 3   |                                      |                                   |  |
| Comments  |   |                                    |   |   |   |   |                                      |                                   |  |
| evel 1 - maximum time at peak temperature during so   | Idering is 10-30 seconds                                  |                                    |   |   |   |   |                                      |                                   |  |
| For more information regarding material composition   | please refer to page 3                                    |                                    |   |   |   |   |                                      |                                   |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *                              | Detailed  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |
| cadmium, hexavalentchromium, polybrominate<br>contains a RoHS restricted substance inexcess<br>encompass all such components. Supplier certif<br>as of the date that Supplier completes this form<br>Company acknowledges that Supplier may hav<br>independently verified information provided by<br>certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip<br>of an applicable quantity limit, please ir<br>ies that it gathered the information it pro-<br>.Supplier acknowledges that Company<br>e relied on informationprovided by othe<br>v others, Supplier agrees that, at a minin<br>and the Supplier enter into a written agre<br>pource of the Supplier's liability and the  | henyl ethers (each a "<br>ndicate below which, i<br>ovides in this form us<br>will rely on this certifiers<br>in completing this<br>num, itssuppliers have<br>eement with respect to<br>Company's remedies | RoHS restricted substance") in exce<br>if any, RoHS exemption you believe<br>ing appropriate methods to ensure if<br>ication in determining the complian<br>form, and that Supplier may not have<br>e provided certifications regarding the<br>to the identified part, the terms and cc<br>for issues that arise regarding inform | ce of its products with European Union membe    | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>l correct to the best of its knowledge and belief,<br>r state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>tions are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |
| RoHS Declaration * 1 - Item(s)   | does not contain RoHS restricted substa   | ances per the definitio  | on above  | Supplier Acceptance                             | * Accepted  |  |  |  |  |
| Exemption: If the declared item does not con applicable exemptions.  | ntain RoHS restricted substances per  | the definition above   | except for defined RoHS exempti   | ons, then select the corresponding response i   | n the RoHS Declaration above and choose all   |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |
| Instructions: Complete all of the required fin<br>Requester) and click on Submit Form to have  | elds on all pages of this form. Select the form returned to the Requester   | he "Accepted" on th  | e Supplier Acceptance drop-down   | . This will display the signature area. Digital | lly sign the declaration (if required by the  |  |  |  |  |
| Supplier Digital Signature Ra  | stislav Drska   | Le   |   |   |   |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight  | Unit of Measure | Level    | Substance                               | CAS        | Exempt | Weight  | Unit of Measure |
|----------------------|---------|-----------------|----------|---|------------|--------|---------|-----------------|
| Coupling Gel         | 0.4     | mg              | Supplier | Dimethyl Cyclosiloxanes                 | 69430-24-6 |        | 0.04    | mg              |
|                      |         |                 | Supplier | Trimethoxy(methyl)silane (C4H12O3Si)    | 1185-55-3  |        | 0.36    | mg              |
| Die                  | 5.13    | mg              | Supplier | Silicon (Si)                            | 7440-21-3  |        | 5.13    | mg              |
| Die Attach           | 0.3     | mg              | Supplier | Silver (Ag)                             | 7440-22-4  |        | 0.225   | mg              |
|                      |         |                 | Supplier | Phenolic Resin-2                        | 54208-63-8 |        | 0.075   | mg              |
| Lead Frame           | 101.703 | mg              | Supplier | Silver (Ag)                             | 7440-22-4  |        | 0.407   | mg              |
|                      |         |                 | Supplier | Zinc (Zn)                               | 7440-66-6  |        | 0.203   | mg              |
|                      |         |                 | Supplier | Iron (Fe)                               | 7439-89-6  |        | 2.64    | mg              |
|                      |         |                 | Supplier | Copper (Cu)                             | 7440-50-8  |        | 98.3    | mg              |
|                      |         |                 | Supplier | Phosphorus (P)                          | 7723-14-0  |        | 0.153   | mg              |
| Mold Compound-White  | 327.22  | mg              | Supplier | Titanium Dioxide (TiO2)                 | 13463-67-7 |        | 81.805  | mg              |
|                      |         |                 | В        | Brominated Bisphenol A Diglycidyl Ether | 40039-93-8 |        | 9.8166  | mg              |
|                      |         |                 | Supplier | Ortho Cresol Novolac Resin              | 29690-82-2 |        | 44.1747 | mg              |
|                      |         |                 | В        | Antimony Trioxide (Sb2O3)               | 1309-64-4  |        | 9.8166  | mg              |
|                      |         |                 | Supplier | Fused Silica (SiO2)                     | 60676-86-0 |        | 163.61  | mg              |
|                      |         |                 | Supplier | Phenolic Resin (Novolac)                | 9003-35-4  |        | 17.9971 | mg              |
| Plating              | 28.5    | mg              | Supplier | Tin (Sn)                                | 7440-31-5  |        | 28.5    | mg              |
| Wire Bond - Au       | 1.65    | mg              | Supplier | Gold (Au)                               | 7440-57-5  |        | 1.65    | mg              |